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P. Walker
1-29-03

S/N 09/785006

PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Aaron M. Schoenfeld

Examiner: Evan Perle

Serial No.: 09/785006

Group Art Unit: 2829

Filed: February 16, 2001

Docket No.: 303.259US

Title: GRINDING TECHNIQUE FOR INTEGRATED CIRCUITS

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on October 18, 2002. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claim 40 and amendment of previously pending claims 11, 15, 22-25, 35, 41 and 43. The specific amendments to individual claims are detailed in the following marked up set of claims.

Please cancel claim 40 and amend the following claims.

11. (Twice Amended) A semiconductor die comprising:

- a first planar surface having circuitry thereon;
- a second planar surface opposite the first planar surface;
- one or more planar perimeter side surfaces, each planar perimeter side surface extending [between] from the first planar surface [and] to the second planar surface;
- [a layer of scribe material forming the planar perimeter side surfaces, the layer of scribe material surrounding the circuitry;] and
- each planar perimeter side surface of the semiconductor die [having] being a ground or polished surface.